

IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (currently amended) A method, comprising:

applying a protective layer to a first side of a wafer, the protective layer covering connection structures on the wafer;

removing, after applying the protective layer, material from a second side of the wafer to thin the wafer[[, without applying adhesive tape in addition to the protective layer]];

separating the wafer into a plurality of chips while simultaneously separating the protective layer to a plurality of sections, each of the sections remaining in contact with a corresponding one of the plurality of chips;

and

attaching at least one of the chips to a substrate by connecting the connection structures to the substrate, wherein [[at least a portion of]] a section of the plurality of sections of the protective layer remaining in contact with said at least one of the chips after separation of the wafer remains between the chip and the substrate after attachment.
2. (cancel)
3. (currently amended) The method of claim [[2]] 23, further comprising partially curing the epoxy after application of the protective layer and prior to removing material from the second side of the wafer.

4. (original) The method of claim 1, wherein the connection structures comprise solder balls.

5. (original) The method of claim 4, wherein attaching at least one of the chips to the substrate comprises applying heat to at least partially melt the solder balls to reflow solder the chip to the substrate.

6. (original) The method of claim 5, wherein the protective layer comprises epoxy, further comprising partially curing the epoxy after application of the protective layer and prior to removing material from the second side of the wafer.

7. (previously presented) The method of claim 3, wherein the connection structures comprise solder balls, wherein attaching at least one of the chips to the substrate comprises applying heat to at least partially melt the solder balls to reflow solder the chip to the substrate, and wherein applying heat to at least partially melt the solder balls also finishes curing the epoxy.

8. – 22. (cancel)

23. (New) The method of claim 1, wherein the protective layer comprises epoxy.

24. (New) The method of claim 1, wherein the at least one of the chips comprises an integrated circuit die.